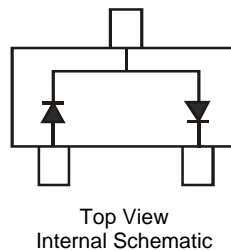


Features

- Fast Switching Speed: Maximum of 50ns
- High Reverse Breakdown Voltage: 300V
- Low Leakage Current: Maximum of 100nA when $V_R = 240V$ at Room Temperature
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- **Qualified to AEC-Q101 Standards for High Reliability**
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

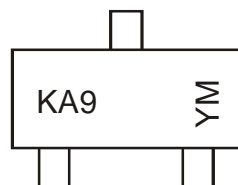
Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin annealed over Copper leadframe. (Lead Free Plating) Solderable per MIL-STD-202, Method 208 ^{e3}
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)


Ordering Information (Notes 4 & 5)

Part Number	Qualification	Case	Packaging
MMBD2004SW-7-F	Commercial	SOT323	3000/Tape & Reel
MMBD2004SWQ-7-F	Automotive	SOT323	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See <http://www.diodes.com> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.
 5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

Marking Information


KA9= Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: Z = 2012)
 M = Month (ex: 9 = September)

Date Code Key

Year	2003	2004	2012	2013	2014	2015	2016	2017	2018
Code	P	R	Z	A	B	C	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V _{RRM}	300	V
Working Peak Reverse Voltage	V _{RWM}	240	V
DC Blocking Voltage	V _R	170	V
RMS Reverse Voltage	V _{R(RMS)}	170	V
Forward Continuous Current	I _F	225	mA
Peak Repetitive Forward Current	I _{FRM}	625	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	4.0	A
		1.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	250	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	300	—	V	I _R = 100μA
Forward Voltage	V _F	—	0.87 1.0	V	I _F = 20mA I _F = 100mA
Peak Reverse Current (Note 7)	I _R	—	100	nA μA	V _R = 240V V _R = 240V, T _J = +150°C
Total Capacitance, per Element	C _T	—	5.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	50	ns	I _F = I _R = 30mA, I _{rr} = 3.0mA, R _L = 100Ω

- Notes: 6. Part mounted on FR-4 PC Board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
7. Short duration pulse test used to minimize self-heating effect.

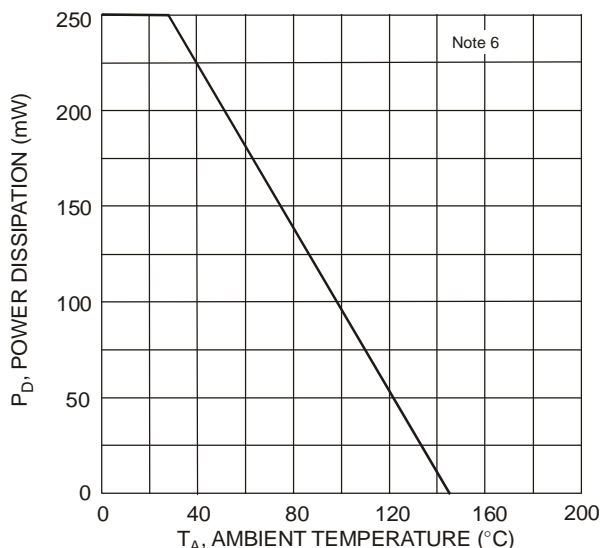


Figure 1 Power Derating Curve, Total Package

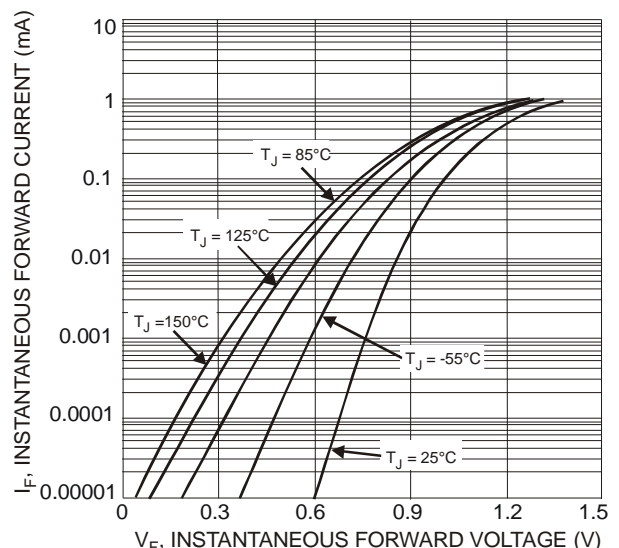


Figure 2 Typical Forward Characteristics, Per Element

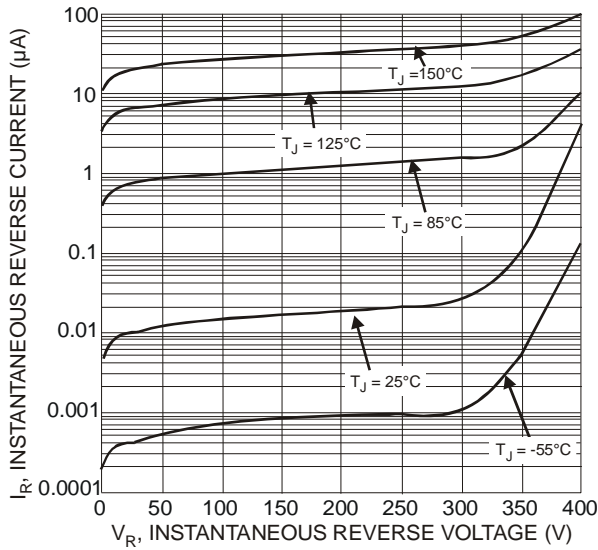


Figure 3 Typical Reverse Characteristics, Per Element

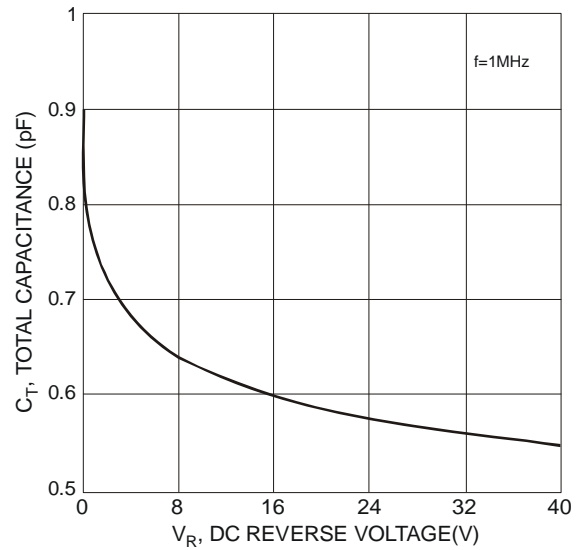
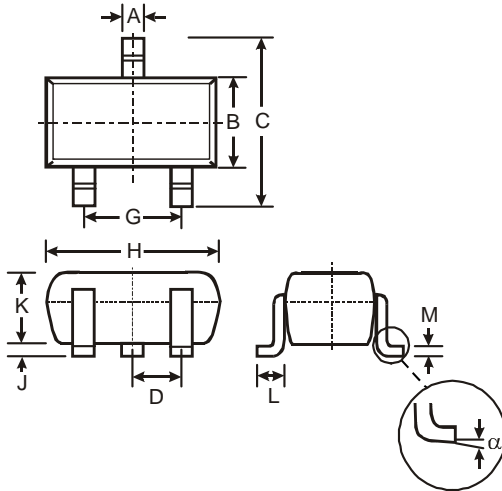


Figure 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

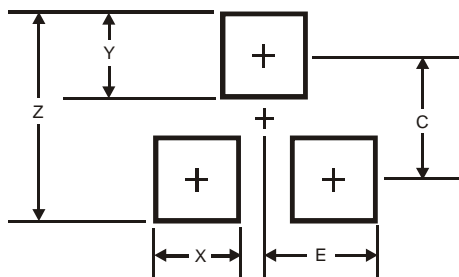


SOT323			
Dim	Min	Max	Typ
A	0.25	0.40	0.30
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	-	-	0.65
G	1.20	1.40	1.30
H	1.80	2.20	2.15
J	0.0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.18	0.11
α	0°	8°	-

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.8
X	0.7
Y	0.9
C	1.9
E	1.0

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